

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hui-suk Yun</td> <td>07/06/2007</td> </tr> <tr> <td>Seung-Eon Kim</td> <td>07/06/2007</td> </tr> </tbody> </table>		Name	Execution Date	Hui-suk Yun	07/06/2007	Seung-Eon Kim	07/06/2007
Name	Execution Date						
Hui-suk Yun	07/06/2007						
Seung-Eon Kim	07/06/2007						
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Postal Code:	307-343						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11775463</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11775463		
Property Type	Number						
Application Number:	11775463						
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Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif							

OP \$40.00 11775463

PATENT

ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION

This is an assignment of the following rights, title and interest (check all that apply):

- United States of America rights, title and interest in the invention*
- Foreign rights, title and interest in the invention*
- United States Patent Application Serial No. _____
Date of Execution: _____ Date of Filing: _____*
- United States Provisional Patent Application Serial No. _____*
- United States Patent No(s). _____*
- International (PCT) Patent Application Serial No. _____*
- Other (specify) _____*

Title of the Invention:

POROUS MATERIAL HAVING HIERARCHICAL PORE STRUCTURE AND PREPARATION METHOD THEREOF

Inventors (assignors):

<i>Name</i>	<i>Address</i>
Hui-suk Yun	#204 13-3 Gacomjeong-Dong, Changwon-Shi, Gyeongsangnam-do, 641-110 Republic of Korea
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Assignee:

<i>Name</i>	<i>Address</i>
Korea Institute of Machinery & Materials	171 Jang-Dong, Yusong-Gu, Daejeon, KIMM, 307-343, Republic of Korea

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the invention identified above and described in the above-identified patent application(s) and /or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the invention to the above-identified Assignee;



Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuation-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures:

Name	Signature/Date
Hui-suk Yun	 July 6, 2007
Seung-Eon Kim	 July 6, 2007